

# MOSFET - Power, Single N-Channel

**40 V, 0.4 mΩ, 553.8 A**

**NTMTS0D4N04CL**

## Features

- Small Footprint (8x8 mm) for Compact Design
- Low  $R_{DS(on)}$  to Minimize Conduction Losses
- Low  $Q_G$  and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

## Typical Applications

- Power Tools, Battery Operated Vacuums
- UAV/Drones, Material Handling
- BMS/Storage, Home Automation

## MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		$V_{DS}$	40	V
Gate-to-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current $R_{\theta JC}$ (Note 2)	Steady State	$T_C = 25^\circ\text{C}$	$I_D$	553.8 A
		$T_C = 100^\circ\text{C}$	$I_D$	394.8 A
		$T_C = 25^\circ\text{C}$	$P_D$	244 W
		$T_C = 100^\circ\text{C}$	$P_D$	122 W
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2)	Steady State	$T_A = 25^\circ\text{C}$	$I_D$	79.8 A
		$T_A = 100^\circ\text{C}$	$I_D$	56.4 A
		$T_A = 25^\circ\text{C}$	$P_D$	5.0 W
		$T_A = 100^\circ\text{C}$	$P_D$	2.5 W
Pulsed Drain Current	$T_A = 25^\circ\text{C}, t_p = 10 \mu\text{s}$	$I_{DM}$	900	A
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55 to +175	$^\circ\text{C}$
Source Current (Body Diode)		$I_S$	203.4	A
Single Pulse Drain-to-Source Avalanche Energy ( $I_{L(pk)} = 70 \text{ A}$ )		$E_{AS}$	4454	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		$T_L$	260	$^\circ\text{C}$

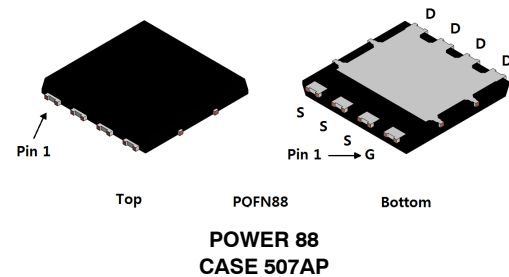
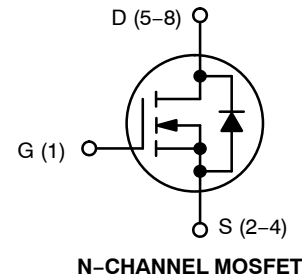
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL RESISTANCE MAXIMUM RATINGS

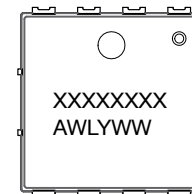
Parameter	Symbol	Value	Unit
Junction-to-Case – Steady State (Note 2)	$R_{\theta JC}$	0.61	$^\circ\text{C/W}$
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	30.1	$^\circ\text{C/W}$

1. Surface-mounted on FR4 board using a 1 in<sup>2</sup> pad size, 1 oz. Cu pad.

$V_{(BR)DSS}$	$R_{DS(on)} \text{ MAX}$	$I_D \text{ MAX}$
40 V	0.4 mΩ @ 10 V	553.8 A
	0.64 mΩ @ 4.5 V	



## MARKING DIAGRAM



XXX = Device Code  
 (8 A–N characters max)  
 A = Assembly Location  
 WL = 2-digit Wafer Lot Code  
 Y = Year Code  
 WW = Work Week Code

## ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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**OFF CHARACTERISTICS**

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = 250\text{ }\mu\text{A}$ , ref to $25^\circ\text{C}$		8.86		mV/ $^\circ\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = 32\text{ V}$	$T_J = 25^\circ\text{C}$		10	$\mu\text{A}$
			$T_J = 125^\circ\text{C}$		250	
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = 20\text{ V}$			100	nA

**ON CHARACTERISTICS** (Note 3)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\text{ }\mu\text{A}$	1.0		2.5	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$	$I_D = 250\text{ }\mu\text{A}$ , ref to $25^\circ\text{C}$		-6.24		mV/ $^\circ\text{C}$
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 50\text{ A}$		0.3	0.4	m $\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 50\text{ A}$		0.45	0.64	
Forward Transconductance	$g_{FS}$	$V_{DS} = 5\text{ V}, I_D = 50\text{ A}$		330		S
Gate Resistance	$R_G$	$T_A = 25^\circ\text{C}$		1.0		$\Omega$

**CHARGES, CAPACITANCES & GATE RESISTANCE**

Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 20\text{ V}$		20600		pF
Output Capacitance	$C_{OSS}$			9500		
Reverse Transfer Capacitance	$C_{RSS}$			390		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 20\text{ V}; I_D = 50\text{ A}$		163		nC
Threshold Gate Charge	$Q_{G(TH)}$	$V_{GS} = 10\text{ V}, V_{DS} = 20\text{ V}; I_D = 50\text{ A}$		29.8		nC
Gate-to-Source Charge	$Q_{GS}$			51		
Gate-to-Drain Charge	$Q_{GD}$			52.1		
Total Gate Charge	$Q_{G(TOT)}$			341		
Voltage Plateau	$V_{GP}$			2.7		

**SWITCHING CHARACTERISTICS,  $V_{GS} = 4.5\text{ V}$**  (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 20\text{ V}, I_D = 50\text{ A}, R_G = 6\text{ }\Omega$		110		ns
Rise Time	$t_r$			147		
Turn-Off Delay Time	$t_{d(OFF)}$			217		
Fall Time	$t_f$			107		

**SWITCHING CHARACTERISTICS,  $V_{GS} = 10\text{ V}$**  (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 10\text{ V}, V_{DS} = 20\text{ V}, I_D = 50\text{ A}, R_G = 6\text{ }\Omega$		45.6		ns
Rise Time	$t_r$			39.8		
Turn-Off Delay Time	$t_{d(OFF)}$			382		
Fall Time	$t_f$			96.4		

**DRAIN-SOURCE DIODE CHARACTERISTICS**

Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 50 A	T <sub>J</sub> = 25°C		0.75	1.2	V
			T <sub>J</sub> = 125°C		0.58		
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, dI <sub>S</sub> /dt = 100 A/μs, I <sub>S</sub> = 50 A			117		ns
Charge Time	t <sub>a</sub>				87		
Discharge Time	t <sub>b</sub>				30		
Reverse Recovery Charge	Q <sub>RR</sub>				336		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

4. Switching characteristics are independent of operating junction temperatures.

## TYPICAL CHARACTERISTICS

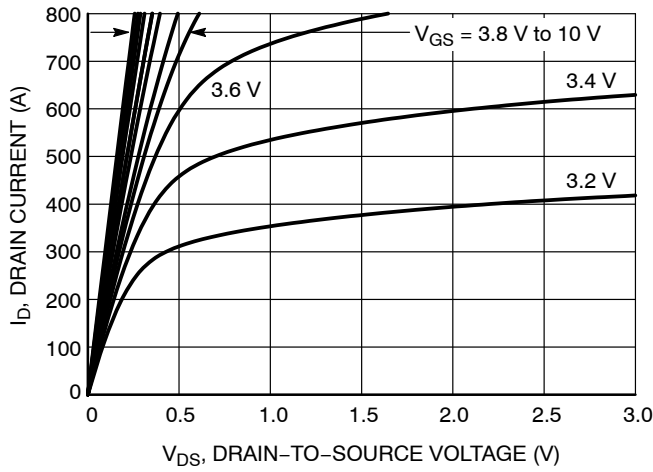


Figure 1. On-Region Characteristics

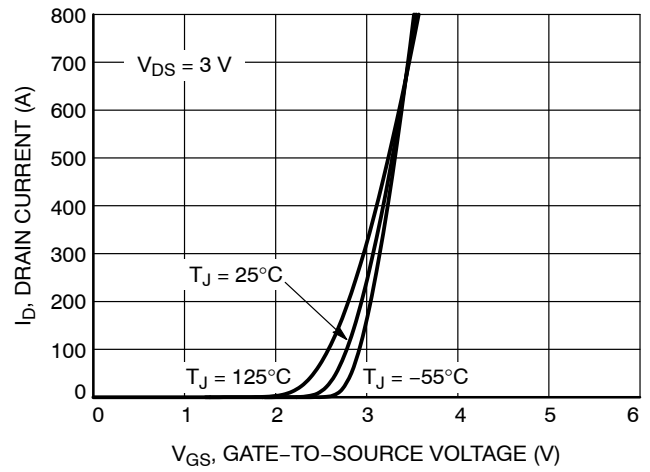


Figure 2. Transfer Characteristics

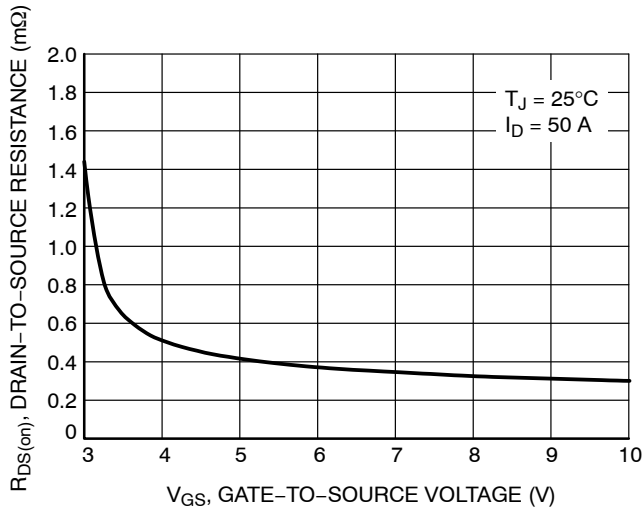


Figure 3. On-Resistance vs. Gate-to-Source Voltage

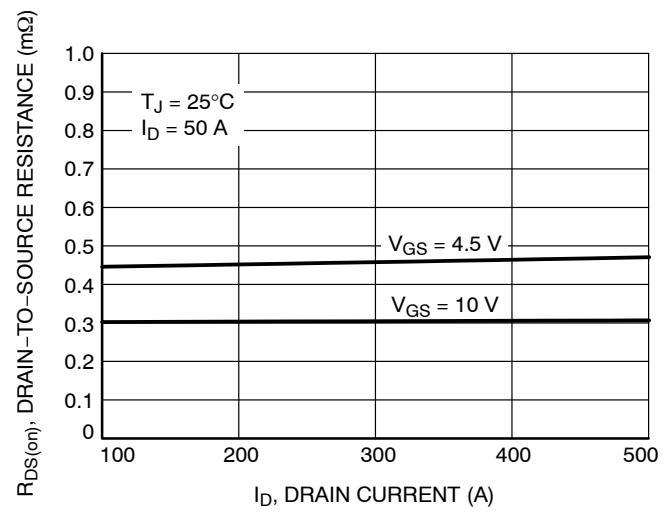


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

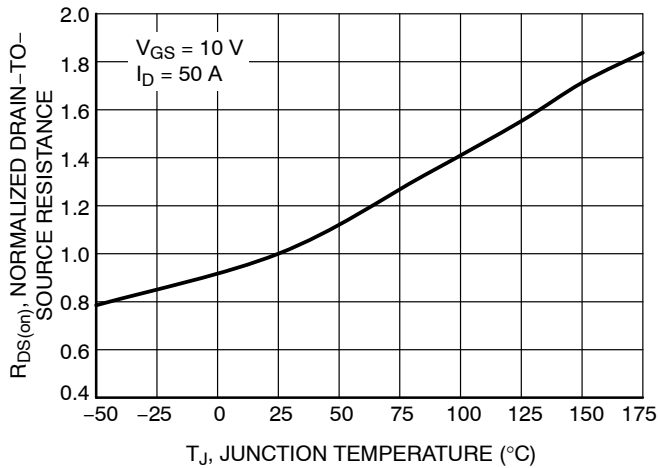


Figure 5. On-Resistance Variation with Temperature

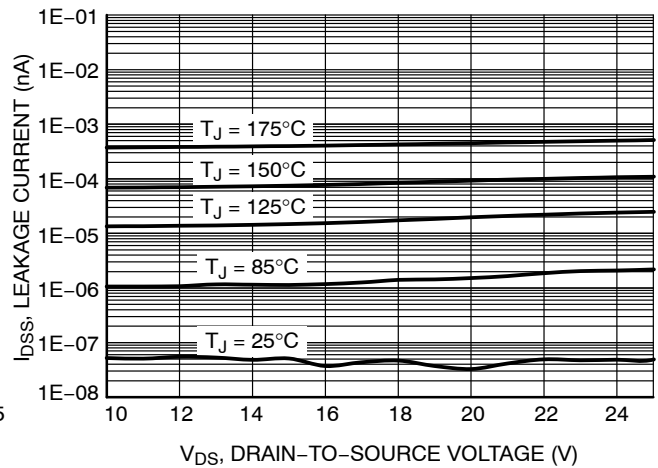


Figure 6. Drain-to-Source Leakage Current vs. Voltage

## TYPICAL CHARACTERISTICS

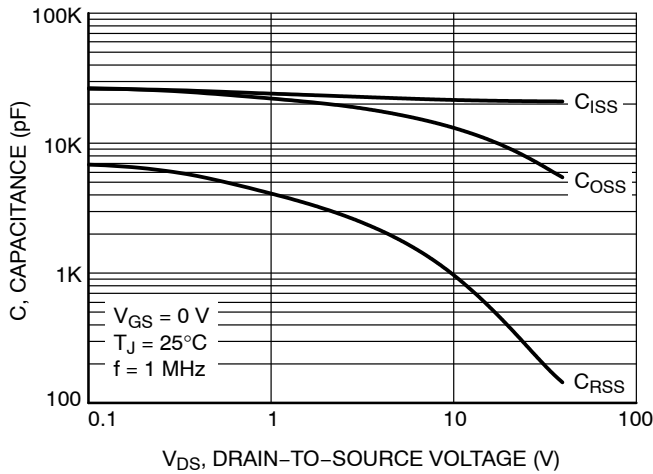


Figure 7. Capacitance Variation

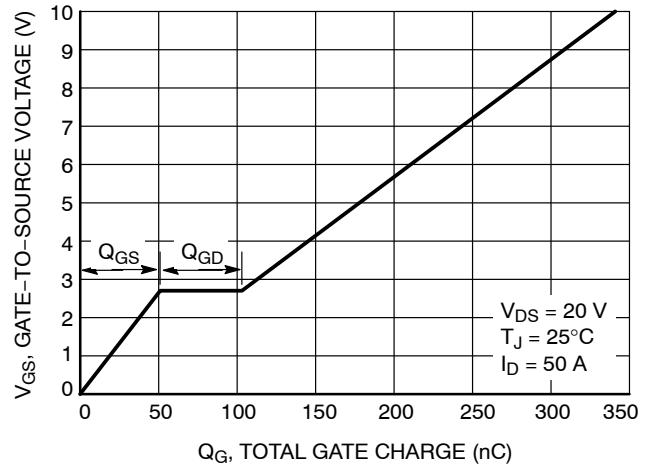


Figure 8. Gate-to-Source Voltage vs. Total Charge

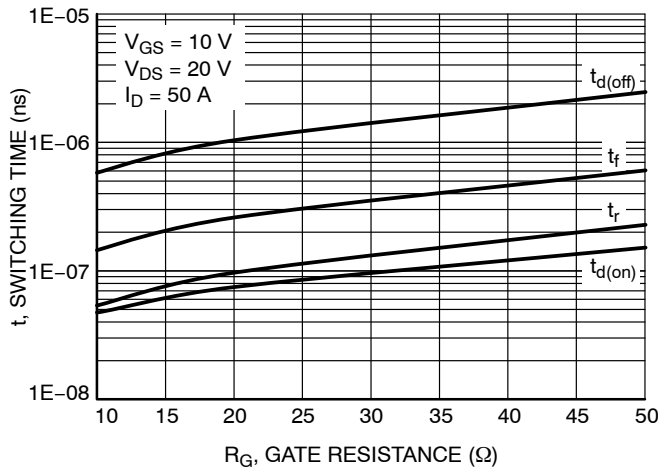


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

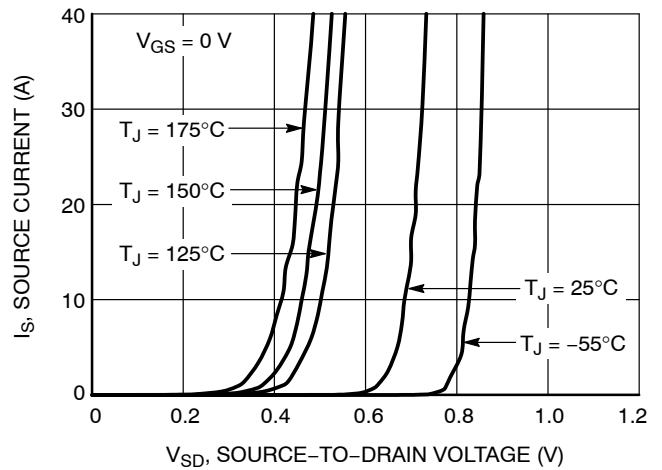


Figure 10. Diode Forward Voltage vs. Current

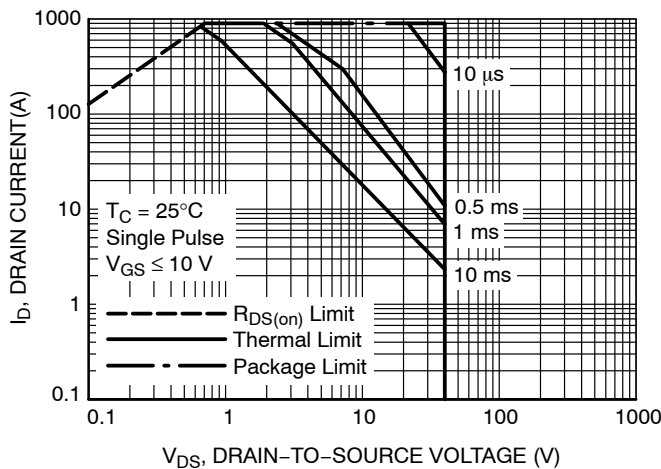


Figure 11. Maximum Rated Forward Biased Safe Operating Area

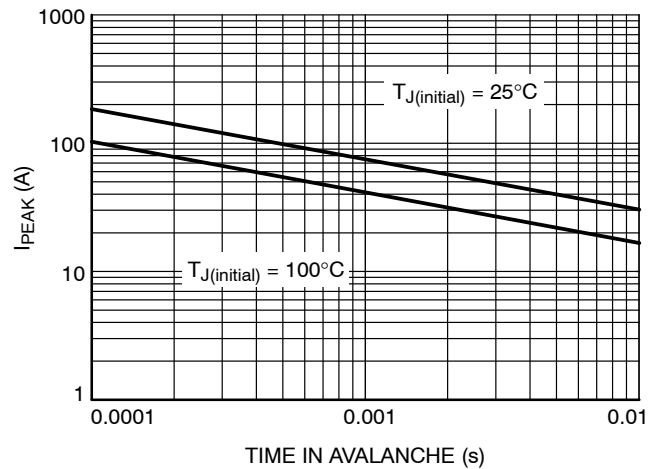


Figure 12.  $I_{PEAK}$  vs. Time in Avalanche

## TYPICAL CHARACTERISTICS

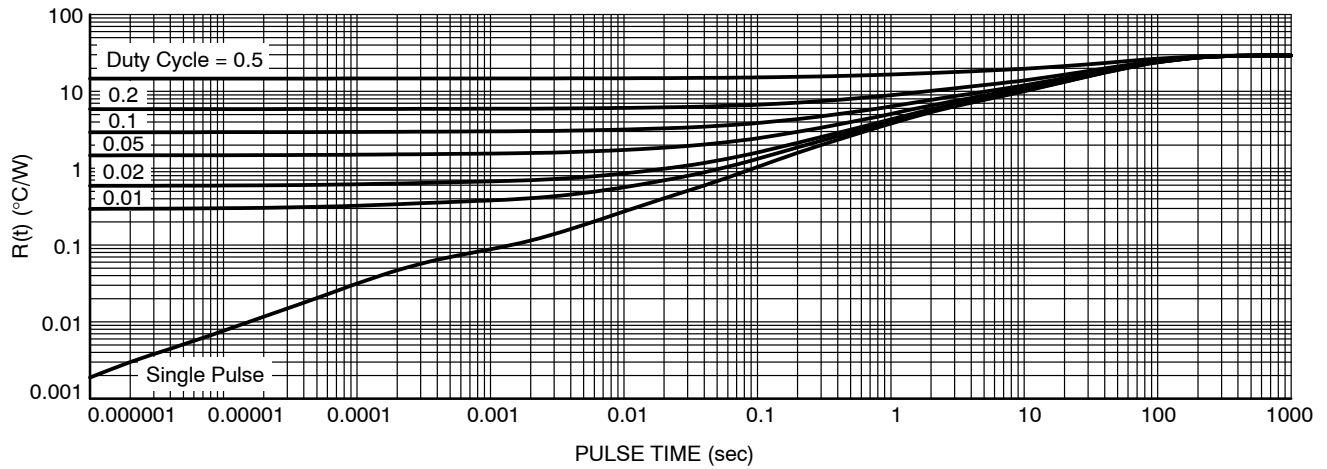


Figure 13. Thermal Characteristics

## DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping <sup>†</sup>
NTMTS0D4N04CLTXG	0D4N04CL	POWER 88 (Pb-Free)	TBD / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.


**TDFNW8 8.30x8.40x1.10, 2.00P**  
**CASE 507AP**  
**ISSUE E**

DATE 08 MAY 2024



\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.00	1.10	1.20
A1	0.00	—	0.05
b	0.90	1.00	1.10
b1	0.35	0.45	0.55
c	0.23	0.28	0.33
D	8.20	8.30	8.40
D1	7.90	8.00	8.10
D2	6.80	6.90	7.00
D3	6.90	7.00	7.10
E	8.30	8.40	8.50
E1	7.80	7.90	8.00
E2	5.24	5.34	5.44
E3	0.25	0.35	0.45
e	2.00 BSC		
e/2	1.00 BSC		
e1	2.70 BSC		
e1/2	1.35 BSC		
K	1.50	1.57	1.70
L	0.64	0.74	0.84
L1	0.67	0.77	0.87
Θ	0°	—	12°

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**TDFNW8 8.30x8.40x1.10, 2.00P**  
**CASE 507AP**  
**ISSUE E**

DATE 08 MAY 2024

**GENERIC  
MARKING DIAGRAM\***



XXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot Code  
Y = Year Code  
WW = Work Week Code

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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